AM26C31 クワッド差動ライン ドライバ

1 特長

- TIA/EIA-422-B と ITU 勧告 V.11 の要件を満たす、または上回る性能
- 低消費電力、I_{CC} = 100µA (標準値)
- 5V 単一電源で動作
- 高速、t_{PLH} = t_{PHL} = 7ns (標準値)
- 小さいパルス歪み、$t_{sk(p)}$ = 0.5ns (標準値)
- 電源オフ状況での高い出力インピーダンス
- AM26LS31 デバイスの改良代替品
- 車載対応 Q-Temp で利用可能
  - 高信頼性の車載用アプリケーション
  - 構成制御と印刷のサポート
  - 車載用規格の認定
- MIL-PRF-38535 準拠の製品については、特に記述のない限り、すべてのパラメータはテスト済みです。その他のすべての製品については、量産プロセスにすべてのパラメータのテストが含まれているとは限りません。

2 アプリケーション

- 化学およびガス センサ
- フィールド トランスミッタ:温度センサおよび圧力センサ
- 軍事:レーダー / ソナー
- モータ制御:ブラシレス DC およびブラシ付き DC
- 軍事 / 航空電子機器用の画像処理
- Modbus 使用の温度センサおよびコントローラ

3 概要

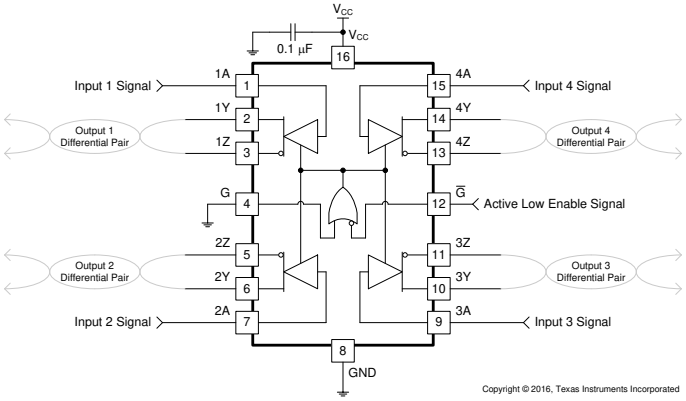
AM26C31 デバイスは、相補出力を備えた差動ライン ドライバであり、TIA/EIA-422-B と ITU (以前の CCITT) の要件を満たすように設計されています。3 ステート出力は、ツイストペアまたは平行線伝送線路などの平衡ラインを駆動するための大電流能力を備え、電源オフ時には高インピーダンス状態になります。イネーブル機能は 4 つのドライバのすべてに共通しており、アクティブ High またはアクティブ Low のイネーブル (G、$\overline{G}$) 入力を選択できます。BiCMOS 回路により、速度を犠牲にすることなく消費電力を低減しています。

AM26C31C デバイスは 0℃～+70℃で動作特性が規定されており、AM26C31I デバイスは -40℃～+85℃で動作特性が規定されています。AM26C31Q デバイスは車載温度範囲 (-40℃～+125℃) で動作特性が規定されており、AM26C31M デバイスは防衛用温度範囲 (-55℃～+125℃) で動作特性が規定されています。

パッケージ情報

部品番号	パッケージ (1)	パッケージ サイズ(2)
AM26C31	CDIP (J、16)	19.56mm × 6.92mm
	PDIP (N、16)	19.3mm × 6.35mm
	SO (NS、16)	10.3mm × 5.3mm
	CFP (W、16)	10.3mm × 6.73mm
	SOIC (D、16)	9.9mm × 3.91mm
	SSOP (DB、16)	6.2mm × 5.3mm
	TSSOP (PW、16)	5.mm × 4.4mm
	LCCC (FK、20)	8.89mm × 8.89mm

(1) 詳細については、セクション 11 を参照してください。
(2) パッケージ サイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。



一般的なアプリケーション図

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4 Pin Configuration and Functions

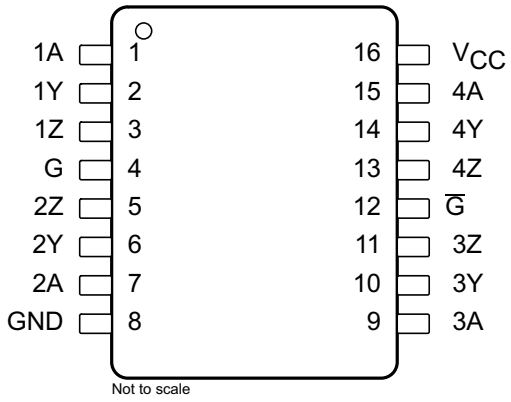

図 4-1. J (CDIP), W (CFP), D (SOIC), DB (SSOP), NS (SO), N (PDIP), or PW (TSSOP) Package 16-Pin (Top View)

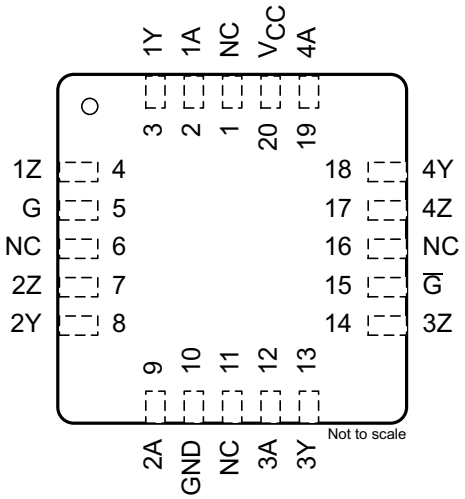

図 4-2. FK (LCCC) Package, 20-Pin (Top View)

表 4-1. Pin Functions

PIN			TYPE	DESCRIPTION
NAME	CDIP, CFP, SOIC, SSOP, SO, PDIP, TSSOP	LCCC		
1A	1	2	I	Driver 1 input
1Y	2	3	O	Driver 1 output
1Z	3	4	O	Driver 1 inverted output
2A	7	9	I	Driver 2 input
2Y	6	8	O	Driver 2 output
2Z	5	7	O	Driver 2 inverted output
3A	9	12	I	Driver 3 input
3Y	10	13	O	Driver 3 output
3Z	11	14	O	Driver 3 inverted output
4A	15	19	I	Driver 3 input
4Y	14	18	O	Driver 3 output
4Z	13	17	O	Driver 3 inverted output
G	4	5	I	Active high enable
$\overline{G}$	12	15	I	Active low enable
GND	8	10	—	Ground pin
NC(1)	—	1, 6, 11, 16	—	No internal connection
V_{CC}	16	20	—	Power pin

(1) NC – No connection

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
V_{CC}	Supply voltage(2)	–0.5	7	V
V_I	Input voltage	–0.5	V_{CC} + 0.5	V
V_{ID}	Differential input voltage	–14	14	V
V_O	Output voltage	–0.5	7	V
I_{IK} I_{OK}	Input or output clamp current		±20	mA
I_O	Output current		±150	mA
	V_{CC} current		200	mA
	GND current	–200		mA
T_J	Operating virtual junction temperature		150	°C
T_{stg}	Storage temperature	–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential voltages, are with respect to the network ground terminal.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{ID}	Differential input voltage			±7		V
V_{IH}	High-level input voltage		2			V
V_{IL}	Low-level input voltage				0.8	V
I_{OH}	High-level output current				–20	mA
I_{OL}	Low-level output current				20	mA
T_A	Operating free-air temperature	AM26C31C	0		70	°C
		AM26C31I	–40		85	
		AM26C31Q	–40		125	
		AM26C31M	–55		125	

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5.4 Thermal Information

THERMAL METRIC[1]		AM26C31								UNIT
		D (SOIC)	DB (SSOP)	PW (TSSOP)	NS (SO)	N (PDIP)	J (CDIP)	W (CFP)	FK (LCCC)	
		16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	16 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance[2] [3]	84.6	102.6	107.5	88.5	60.6	—	—	—	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	43.5	48.7	38.4	46.2	48.1	39.3[4]	58.9[4]	37.1[4]	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	43.2	54.3	53.7	50.7	40.6	56.4[4]	109.3[4]	36.2[4]	°C/W
ψ_{JT}	Junction-to-top characterization parameter	10.4	11.8	3.2	13.5	27.5	—	—	—	°C/W
ψ_{JB}	Junction-to-board characterization parameter	42.8	53.5	53.1	50.3	40.3	—	—	—	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	n/a	n/a	n/a	n/a	n/a	12[4]	5.7[4]	4.3[4]	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.
(2) Maximum power dissipation is a function of $T_{J(max)}$, $R_{\theta JA}$, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_{J(max)} – T_A) / R_{\theta JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
(3) The package thermal impedance is calculated in accordance with JESD 51-7.
(4) Modelling assumption: MIL-STD-883 for $R_{\theta JC(top)}$ and $R_{\theta JC(bot)}$ JESD51 for $R_{\theta JB}$.

5.5 Electrical Characteristics: AM26C31C and AM26C31I

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP[1]	MAX	UNIT
V_{OH}	High-level output voltage	I_O = –20mA		2.4	3.4		V
V_{OL}	Low-level output voltage	I_O = 20mA			0.2	0.4	V
V_{OD}	Differential output voltage magnitude	R_L = 100Ω, see 図 6-1		2	3.1		V
$\Delta\lvert V_{OD}\rvert$	Change in magnitude of differential output voltage[2]	R_L = 100Ω, see 図 6-1				±0.4	V
V_{OC}	Common-mode output voltage	R_L = 100Ω, see 図 6-1				3	V
$\Delta\lvert V_{OC}\rvert$	Change in magnitude of common-mode output voltage[2]	R_L = 100Ω, see 図 6-1				±0.4	V
I_I	Input current	$V_I = V_{CC}$ or GND				±1	µA
$I_{O(off)}$	Driver output current with power off	V_{CC} = 0	V_O = 6V			100	µA
			V_O = –0.25V			–100	
I_{OS}	Driver output short-circuit current	V_O = 0		–30		–150	mA
I_{OZ}	High-impedance off-state output current	V_O = 2.5V				20	µA
		V_O = 0.5V				–20	
I_{CC}	Quiescent supply current	I_O = 0	V_I = 0 or 5V			100	µA
			V_I = 2.4V or 0.5V[3]		1.5	3	mA
C_i	Input capacitance				6		pF

(1) All typical values are at V_{CC} = 5V and T_A = 25°C.
(2) $\Delta\lvert V_{OD}\rvert$ and $\Delta\lvert V_{OC}\rvert$ are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.
(3) This parameter is measured per input. All other inputs are at 0V or 5V.

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5.6 Electrical Characteristics: AM26C31Q and AM26C31M

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP(1)	MAX	UNIT
V_{OH}	High-level output voltage	I_O = –20mA		2.2	3.4		V
V_{OL}	Low-level output voltage	I_O = 20mA			0.2	0.4	V
V_{OD}	Differential output voltage magnitude	R_L = 100Ω, see 図 6-1		2	3.1		V
$\Delta\|V_{OD}\|$	Change in magnitude of differential output voltage(2)	R_L = 100Ω, see 図 6-1				±0.4	V
V_{OC}	Common-mode output voltage	R_L = 100Ω, see 図 6-1				3	V
$\Delta\|V_{OC}\|$	Change in magnitude of common-mode output voltage(2)	R_L = 100Ω, see 図 6-1				±0.4	V
I_I	Input current	V_I = V_{CC} or GND				±1	µA
$I_{O(off)}$	Driver output current with power off	V_{CC} = 0	V_O = 6V			100	µA
			V_O = –0.25V			–100	
I_{OS}	Driver output short-circuit current	V_O = 0				–170	mA
I_{OZ}	High-impedance off-state output current	V_O = 2.5V				20	µA
		V_O = 0.5V				–20	
I_{CC}	Quiescent supply current	I_O = 0	V_I = 0 or 5V			100	µA
			V_I = 2.4V or 0.5V(3)			3.2	mA
C_i	Input capacitance				6		pF

(1) All typical values are at V_{CC} = 5V and T_A = 25°C.
(2) $\Delta|V_{OD}|$ and $\Delta|V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.
(3) This parameter is measured per input. All other inputs are at 0V or 5V.

5.7 Switching Characteristics: AM26C31C and AM26C31I

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	S1 is open, see 図 6-2	3	7	12	ns
t_{PHL}	Propagation delay time, high-to-low-level output		3	7	12	
$t_{sk(p)}$	Pulse skew time ($\|t_{PLH} – t_{PHL}\|$)	S1 is open, see 図 6-2		0.5	4	ns
$t_{r(OD)}$, $t_{f(OD)}$	Differential output rise and fall times	S1 is open, see 図 6-3		5	10	ns
t_{PZH}	Output enable time to high level	S1 is closed, see 図 6-4		10	19	ns
t_{PZL}	Output enable time to low level			10	19	
t_{PHZ}	Output disable time from high level	S1 is closed, see 図 6-4		7	16	ns
t_{PLZ}	Output disable time from low level			7	16	
C_{pd}	Power dissipation capacitance (each driver)(2)	S1 is open, see 図 6-2		170		pF

(1) All typical values are at V_{CC} = 5V and T_A = 25°C.
(2) C_{pd} is used to estimate the switching losses according to $P_D = C_{pd} \times V_{CC}^2 \times f$, where f is the switching frequency.

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5.8 Switching Characteristics: AM26C31Q and AM26C31M

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	S1 is open, see 図 6-2		7	12	ns
t_{PHL}	Propagation delay time, high-to-low-level output			6.5	12	
$t_{sk(p)}$	Pulse skew time ($\|t_{PLH} - t_{PHL}\|$)	S1 is open, see 図 6-2		0.5	4	ns
$t_{r(OD)}$, $t_{f(OD)}$	Differential output rise and fall times	S1 is open, see 図 6-3		5	12	ns
t_{PZH}	Output enable time to high level	S1 is closed, see 図 6-4		10	19	ns
t_{PZL}	Output enable time to low level			10	19	
t_{PHZ}	Output disable time from high level	S1 is closed, see 図 6-4		7	16	ns
t_{PLZ}	Output disable time from low level			7	16	
C_{pd}	Power dissipation capacitance (each driver)(2)	S1 is open, see 図 6-2		100		pF

(1) All typical values are at V_{CC} = 5V and T_A = 25°C.
(2) C_{pd} is used to estimate the switching losses according to $P_D = C_{pd} \times V_{CC}^2 \times f$, where f is the switching frequency.

5.9 Typical Characteristics

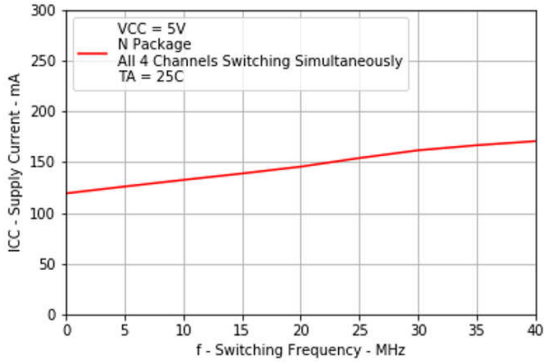


図 5-1. Supply Current vs Switching Frequency

6 Parameter Measurement Information

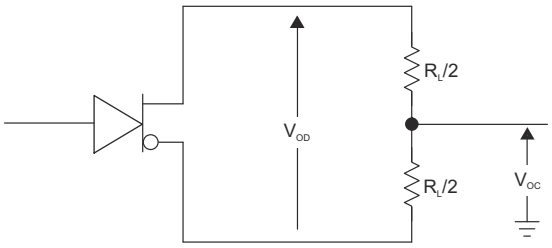
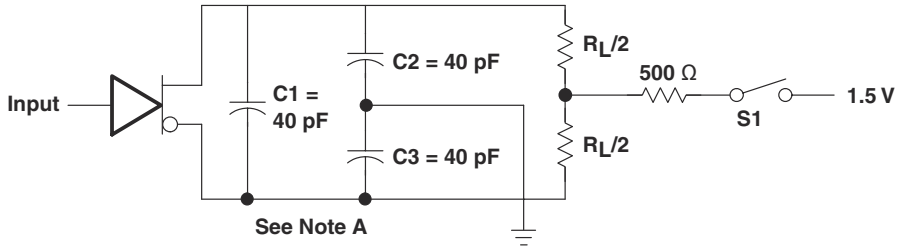
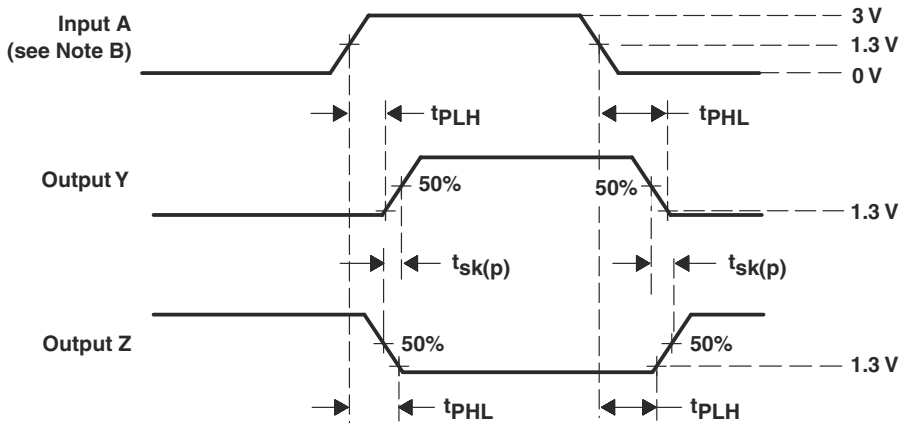


図 6-1. Differential and Common-Mode Output Voltages



TEST CIRCUIT



A. C1, C2, and C3 include probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1MHz, duty cycle ≤ 50%, and t_r, t_f ≤ 6ns.

図 6-2. Propagation Delay Time and Skew Waveforms and Test Circuit

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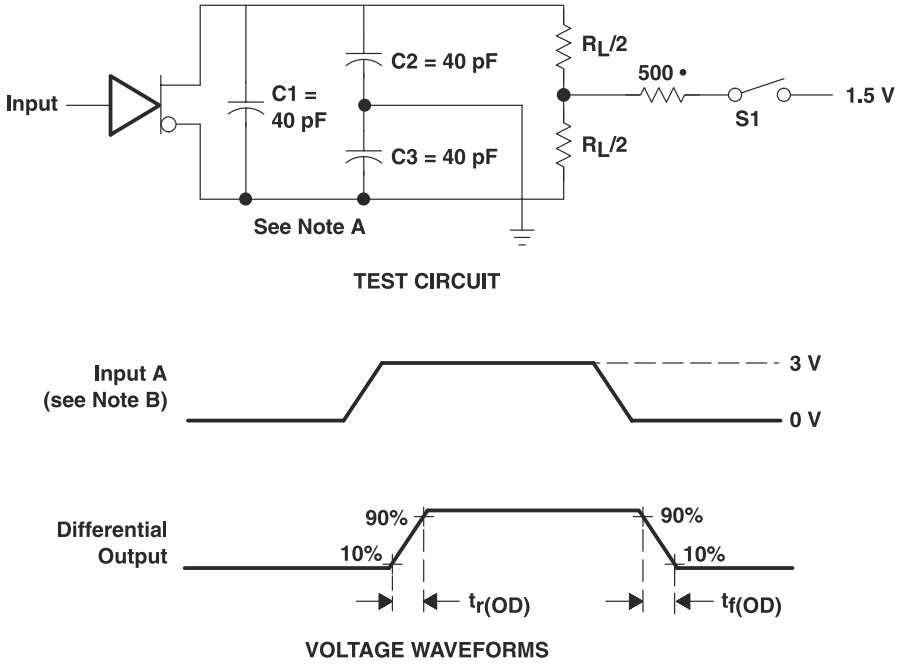
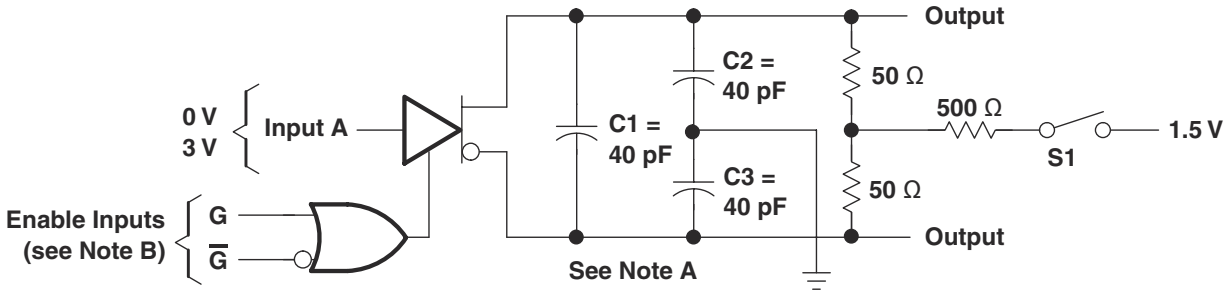


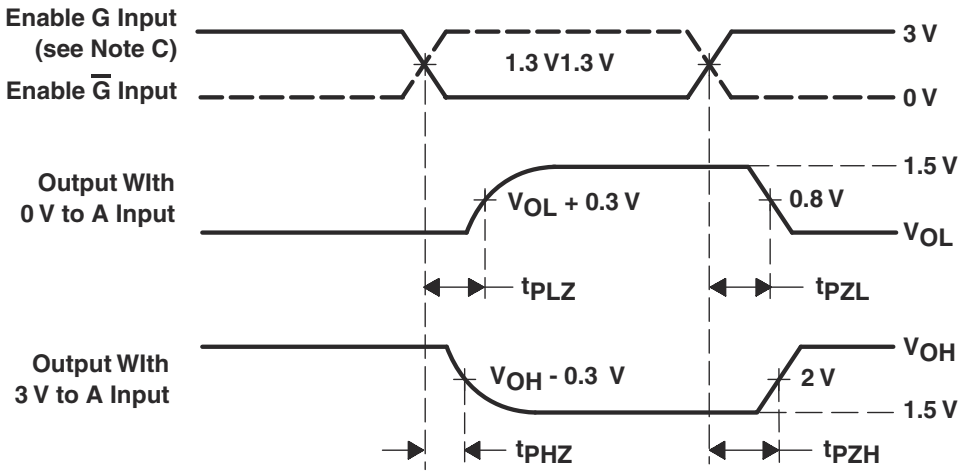
A. C1, C2, and C3 include probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1MHz, duty cycle ≤ 50%, and t_r, t_f ≤ 6ns.

図 6-3. Differential-Output Rise and Fall-Time Waveforms and Test Circuit



TEST CIRCUIT



VOLTAGE WAVEFORMS

A. C1, C2, and C3 include probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1MHz, duty cycle ≤ 50%, and t_r, t_f ≤ 6ns.
C. Each enable is tested separately.

図 6-4. Output Enable and Disable Time Waveforms and Test Circuit

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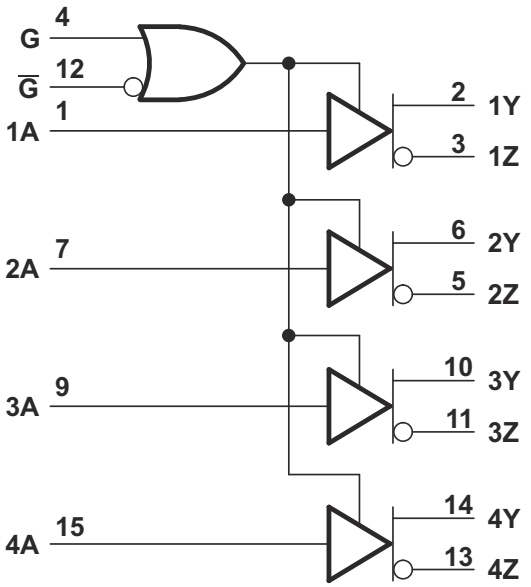
7 Detailed Description

7.1 Overview

The AM26C31 is a quadruple differential line driver with complementary outputs. The device is designed to meet the requirements of TIA/EIA-422-B and ITU (formerly CCITT), and it is generally used to communicate over relatively long wires in noisy environments.

7.2 Functional Block Diagrams



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Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

図 7-1. Logic Diagram (Positive Logic)

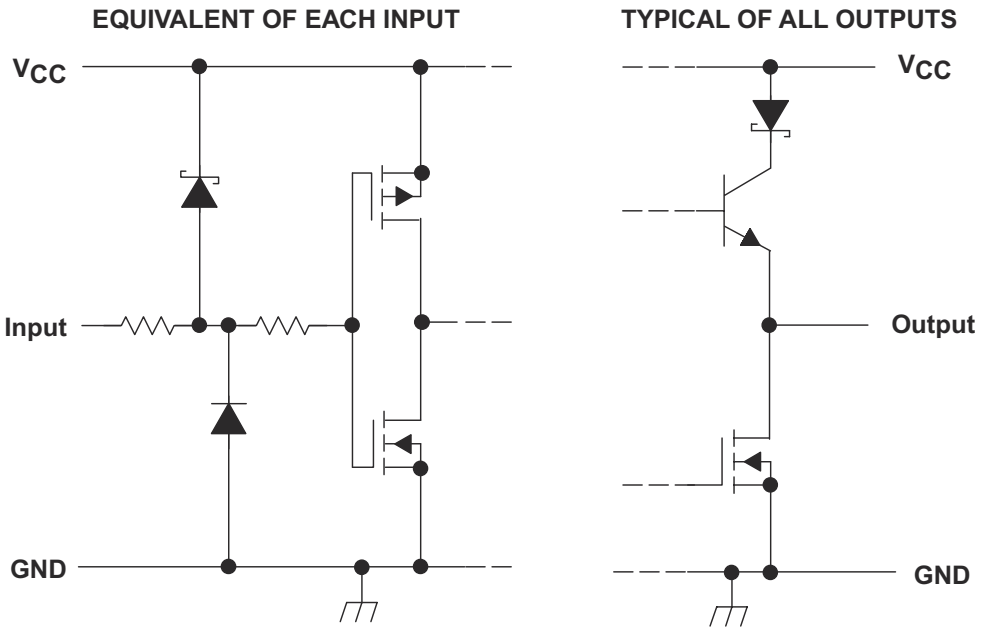

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図 7-2. Schematics of Inputs and Outputs

7.3 Feature Description

7.3.1 Active-High and Active-Low

The device can be configured using the G and $\overline{G}$ logic inputs to select transmitter output. A logic high on the G pin or a logic low on the $\overline{G}$ pin enables the device to operate. These pins are simply a way to configure the logic to match that of the receiving or transmitting controller or microprocessor.

7.3.2 Operates From a Single 5V Supply

Both the logic and transmitters operate from a single 5V rail, making designs much more simple. The line drivers and receivers can operate off the same rail as the host controller or a similar low voltage supply, thus simplifying power structure.

7.4 Device Functional Modes

表 7-1 lists the functional modes of the AM26C31.

表 7-1. Function Table (Each Driver)(1)

INPUT A	ENABLES		OUTPUTS	
	G	$\overline{G}$	Y	Z
H	H	X	H	L
L	H	X	L	H
H	X	L	H	L
L	X	L	L	H
X	L	H	Z	Z

(1) H = High level,
L = Low level,
X = Irrelevant,
Z = High impedance (off)

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8 Application Information Disclaimer

注

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8.1 Application Information

When designing a system that uses drivers, receivers, and transceivers that comply with RS-422, proper cable termination is essential for highly reliable applications with reduced reflections in the transmission line. Because RS-422 allows only one driver on the bus, if termination is used, it is placed only at the end of the cable near the last receiver. Factors to consider when determining the type of termination usually are performance requirements of the application and the ever-present factor, cost. The different types of termination techniques discussed are unterminated lines, parallel termination, AC termination, and multipoint termination. For laboratory experiments, 100 feet of 100Ω, 24-AWG, twisted-pair cable (Bertek) was used. A single driver and receiver, TI AM26C31C and AM26C32C, respectively, were tested at room temperature with a 5V supply voltage. To show voltage waveforms related to transmission-line reflections, the first plot shows output waveforms from the driver at the start of the cable (A/B); the second plot shows input waveforms to the receiver at the far end of the cable (Y).

8.2 Typical Application

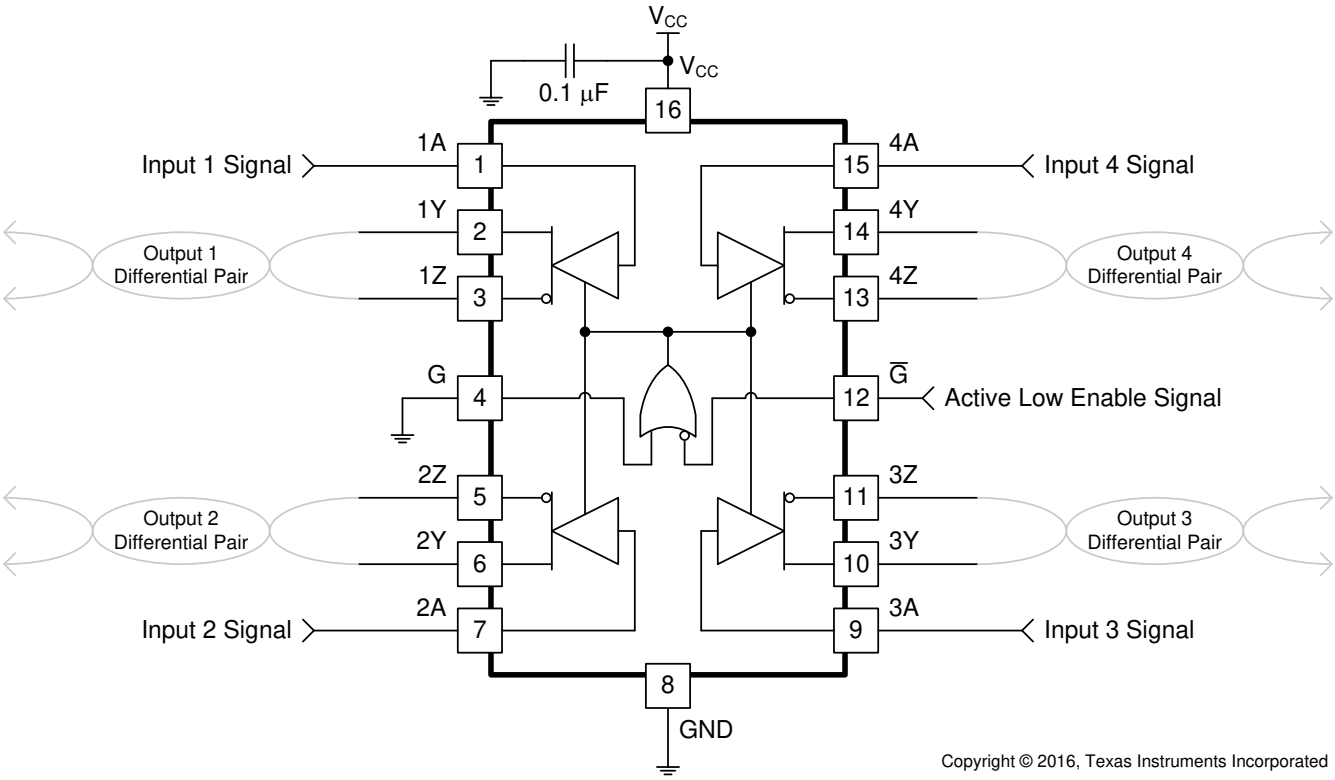

図 8-1. Differential Terminated Configuration With All Channels and Active Low Enable Used

8.2.1 Design Requirements

Resistor and capacitor (if used) termination values are shown for each laboratory experiment, but vary from system to system. For example, the termination resistor, R_T, must be within 20% of the characteristic impedance, Zo, of the cable and can vary from about 80Ω to 120Ω.

8.2.2 Detailed Design Procedure

Ensure values in *Absolute Maximum Ratings* are not exceeded.

Supply voltage, V_{IH}, and V_{IL} must comply with *Recommended Operating Conditions*.

8.2.3 Application Curve

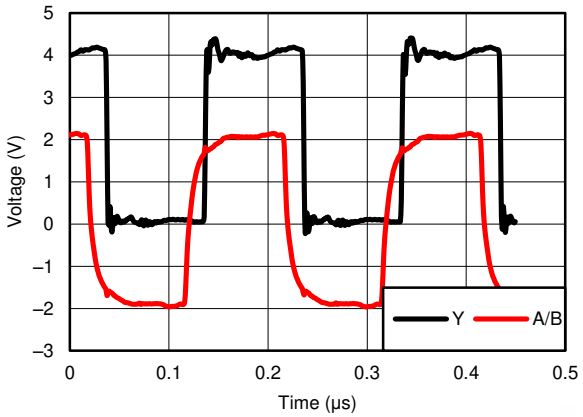

図 8-2. Differential 120Ω Terminated Output Waveforms (Cat 5E Cable)

8.3 Power Supply Recommendations

Place 0.1µF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high impedance power supplies.

8.4 Layout

8.4.1 Layout Guidelines

For best operational performance of the device, use good PCB layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit as a whole, as well as the operational amplifier. Bypass capacitors are used to reduce the coupled noise by providing low impedance power sources local to the analog circuitry.
  - Connect low-ESR, 0.1-µF ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for single-supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most effective methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes. A ground plane helps distribute heat and reduces EMI noise pickup. Make sure to physically separate digital and analog grounds, paying attention to the flow of the ground current.
- To reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If it is not possible to keep them separate, it is much better to cross the sensitive trace perpendicular as opposed to in parallel with the noisy trace.
- Place the external components as close to the device as possible. Keeping RF and RG close to the inverting input minimizes parasitic capacitance.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.

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8.4.2 Layout Example

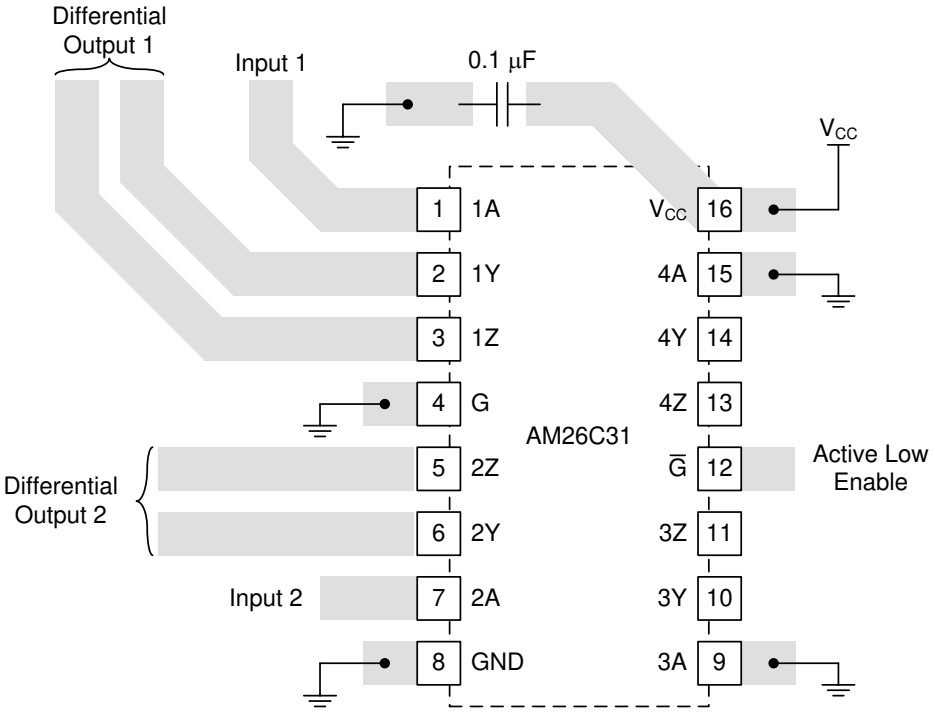

図 8-3. Trace Layout on PCB and Recommendations

9 Device and Documentation Support

9.1 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

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9.5 用語集

テキサス・インスツルメンツ用語集　　この用語集には、用語や略語の一覧および定義が記載されています。

10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision O (June 2016) to Revision P (March 2024)	Page
• 「製品情報」表を「パッケージ情報」表に変更	1
• Changed *Thermal Information* table	5
• Changed 図 5-1	7
• Changed 図 6-1	8

Changes from Revision N (October 2011) to Revision O (Februrary 2014)	Page
• 「特長」セクションを更新。「アプリケーション」セクション、「デバイス情報」表、「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加	1
• 「注文情報」表を削除 (データシートの末尾にある POA を参照)	1
• Changed *Thermal Information* table	5

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Changes from Revision M (June 2008) to Revision N (October 2011)	Page
• Changed units to mA from µA to fix units typo	4

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9163901M2A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9163901M2A AM26C31M
5962-9163901MEA	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9163901MEA AM26C31M
5962-9163901MFA	Active	Production	CFP (W) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9163901MFA AM26C31M
5962-9163901Q2A	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9163901Q2A AM26C31 MFKB
5962-9163901QEA	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9163901QEA AM26C31MJB
5962-9163901QFA	Active	Production	CFP (W) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9163901QFA AM26C31MWB
AM26C31CD	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	0 to 70	AM26C31C
AM26C31CDBR	Obsolete	Production	SSOP (DB) | 16	-	-	Call TI	Call TI	0 to 70	26C31
AM26C31CDR	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	0 to 70	AM26C31C
AM26C31CN	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	AM26C31CN
AM26C31CNSR	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU | NIPDAU	Level-1-260C-UNLIM	0 to 70	26C31
AM26C31ID	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-40 to 85	AM26C31I
AM26C31IDBR	Active	Production	SSOP (DB) | 16	2000 | LARGE T&R	Yes	NIPDAU | NIPDAU	Level-1-260C-UNLIM	-40 to 85	26C31I
AM26C31IDR	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM26C31I
AM26C31IDRG4	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-40 to 85	AM26C31I
AM26C31IN	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	AM26C31IN
AM26C31INSR	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU | NIPDAU	Level-1-260C-UNLIM	-40 to 85	26C31I
AM26C31IPW	Obsolete	Production	TSSOP (PW) | 16	-	-	Call TI	Call TI	-40 to 85	26C31I
AM26C31IPWR	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	26C31I

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
AM26C31IPWRG4	Obsolete	Production	TSSOP (PW) | 16	-	-	Call TI	Call TI	-40 to 85	26C31I
AM26C31MFKB	Active	Production	LCCC (FK) | 20	55 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9163901Q2A AM26C31 MFKB
AM26C31MJB	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9163901QE A AM26C31MJB
AM26C31MWB	Active	Production	CFP (W) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9163901QF A AM26C31MWB
AM26C31QD	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-40 to 125	AM26C31Q
AM26C31QDG4	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-40 to 125	26C31Q
AM26C31QDR	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AM26C31Q
AM26C31QDRG4	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	26C31Q

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF AM26C31, AM26C31M :

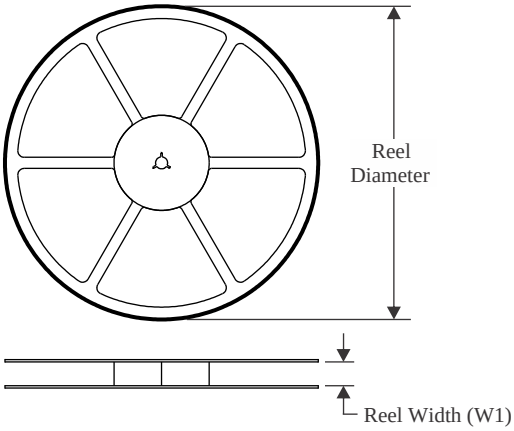
- Catalog : AM26C31
- Enhanced Product : AM26C31-EP, AM26C31-EP
- Military : AM26C31M

NOTE: Qualified Version Definitions:

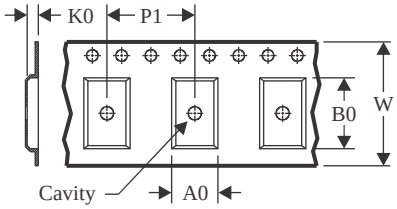
- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

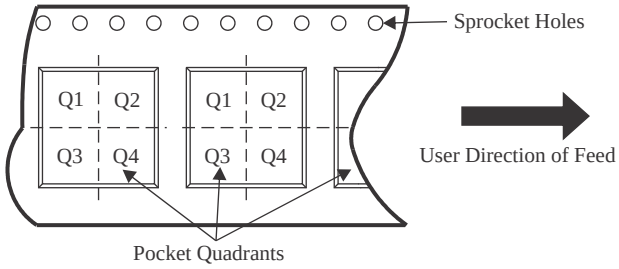


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

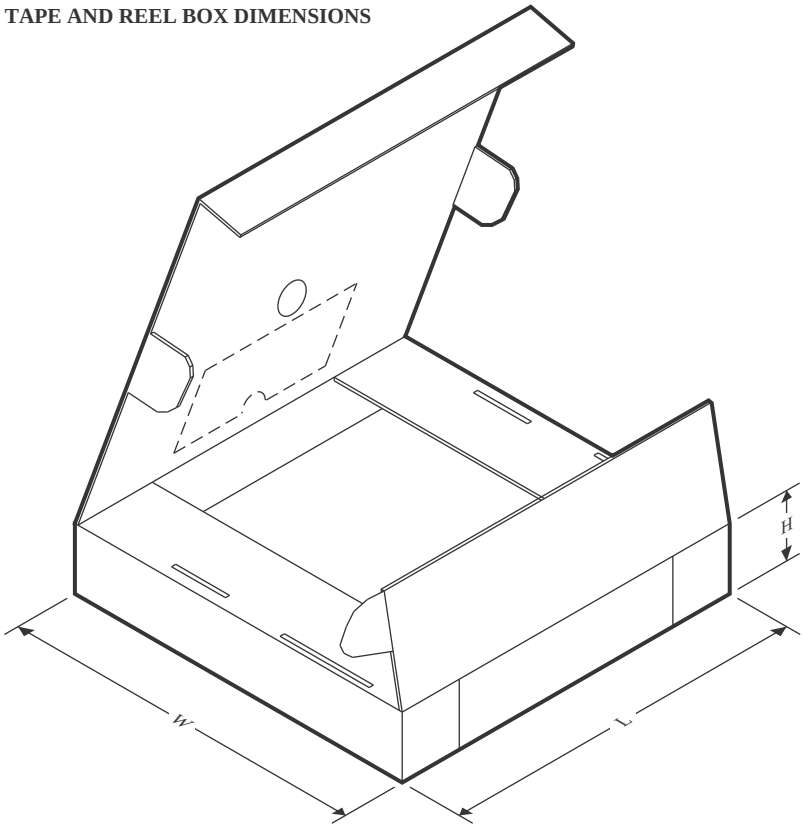
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
AM26C31CNSR	SOP	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
AM26C31CNSR	SOP	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
AM26C31IDBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
AM26C31IDBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
AM26C31IDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26C31IDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26C31INSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
AM26C31INSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
AM26C31IPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
AM26C31IPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
AM26C31QDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
AM26C31QDRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

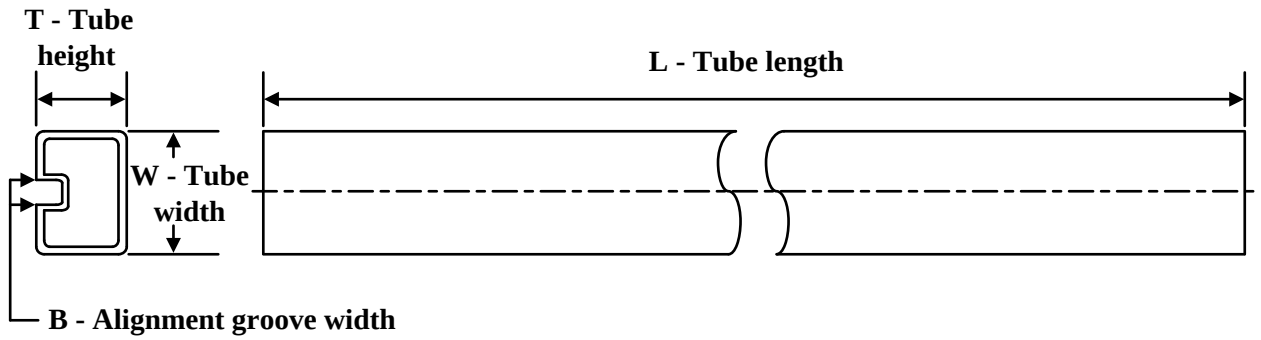
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
AM26C31CNSR	SOP	NS	16	2000	353.0	353.0	32.0
AM26C31CNSR	SOP	NS	16	2000	356.0	356.0	35.0
AM26C31IDBR	SSOP	DB	16	2000	353.0	353.0	32.0
AM26C31IDBR	SSOP	DB	16	2000	356.0	356.0	35.0
AM26C31IDR	SOIC	D	16	2500	353.0	353.0	32.0
AM26C31IDR	SOIC	D	16	2500	340.5	336.1	32.0
AM26C31INSR	SOP	NS	16	2000	353.0	353.0	32.0
AM26C31INSR	SOP	NS	16	2000	356.0	356.0	35.0
AM26C31IPWR	TSSOP	PW	16	2000	367.0	367.0	35.0
AM26C31IPWR	TSSOP	PW	16	2000	353.0	353.0	32.0
AM26C31QDR	SOIC	D	16	2500	353.0	353.0	32.0
AM26C31QDRG4	SOIC	D	16	2500	353.0	353.0	32.0

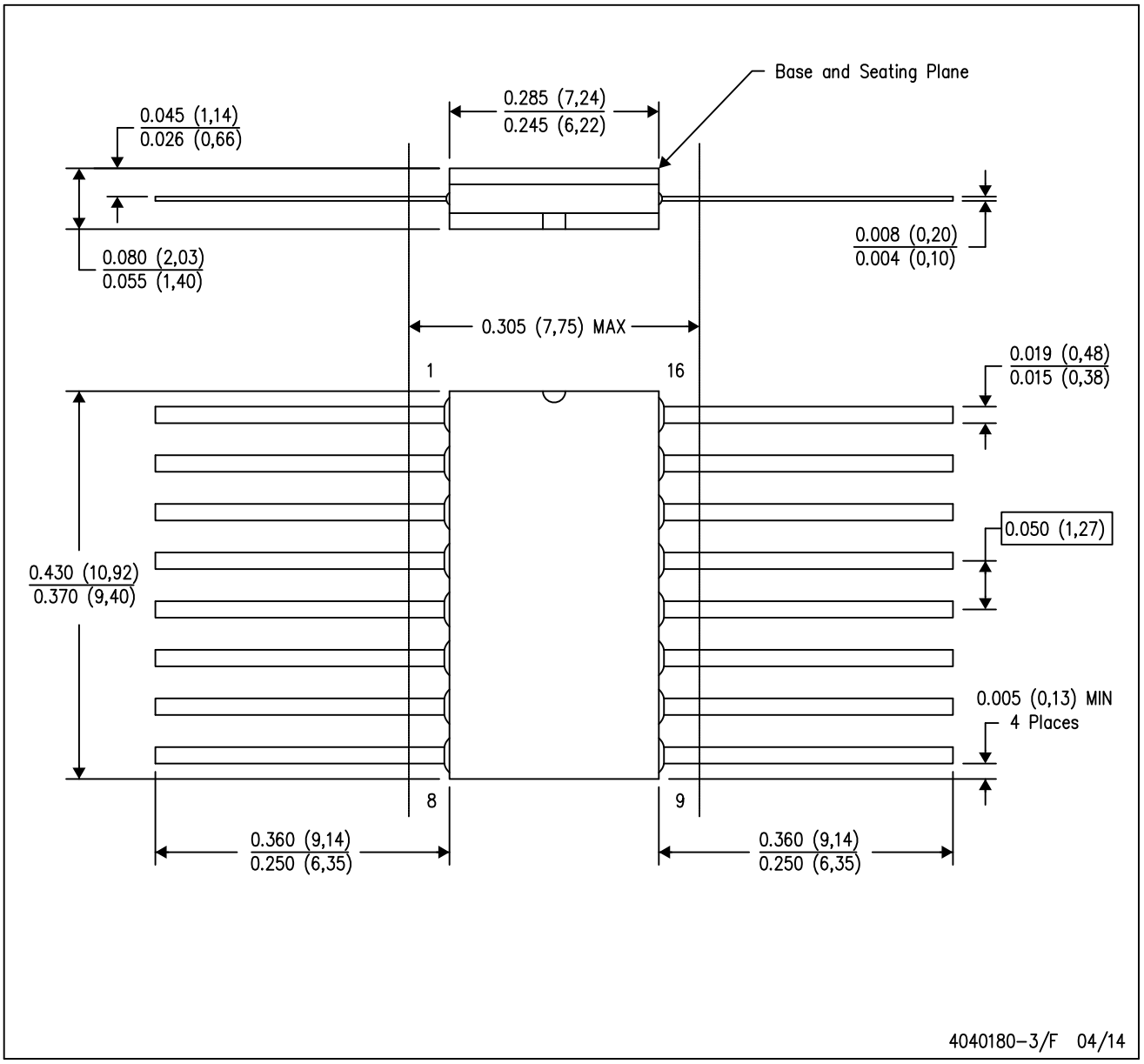
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9163901M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9163901MFA	W	CFP	16	25	506.98	26.16	6220	NA
5962-9163901Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9163901QFA	W	CFP	16	25	506.98	26.16	6220	NA
AM26C31CN	N	PDIP	16	25	506	13.97	11230	4.32
AM26C31IN	N	PDIP	16	25	506	13.97	11230	4.32
AM26C31INE4	N	PDIP	16	25	506	13.97	11230	4.32
AM26C31MFKB	FK	LCCC	20	55	506.98	12.06	2030	NA
AM26C31MWB	W	CFP	16	25	506.98	26.16	6220	NA

W (R–GDFP–F16) CERAMIC DUAL FLATPACK



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP2–F16

GENERIC PACKAGE VIEW

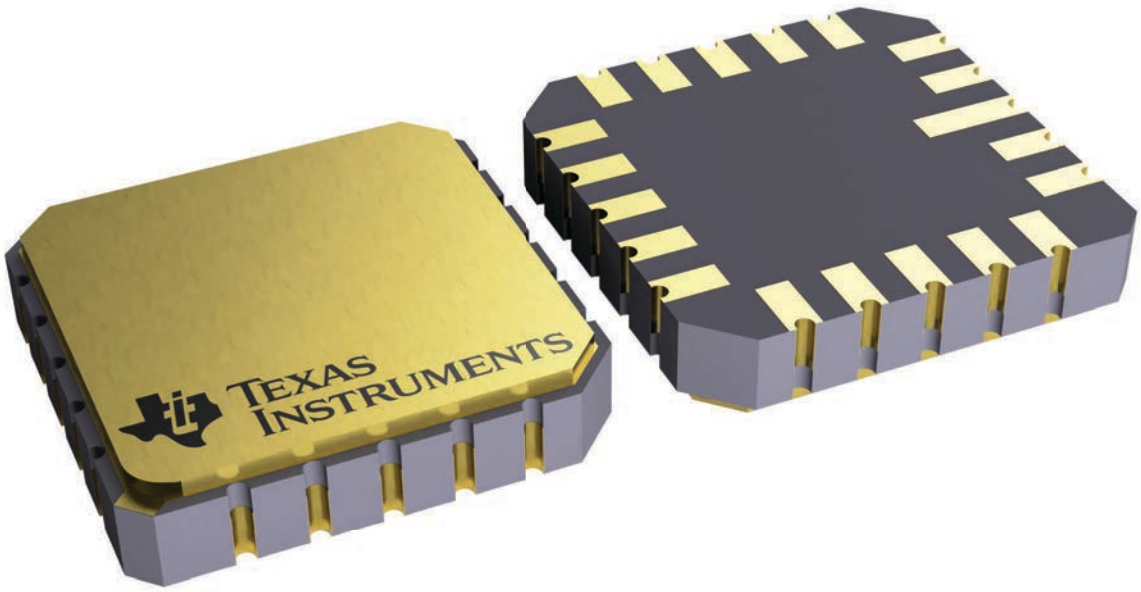
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

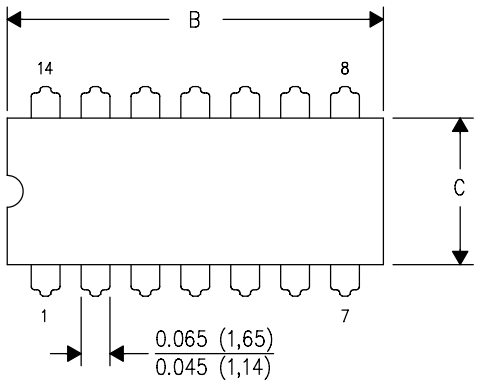


4229370VA\

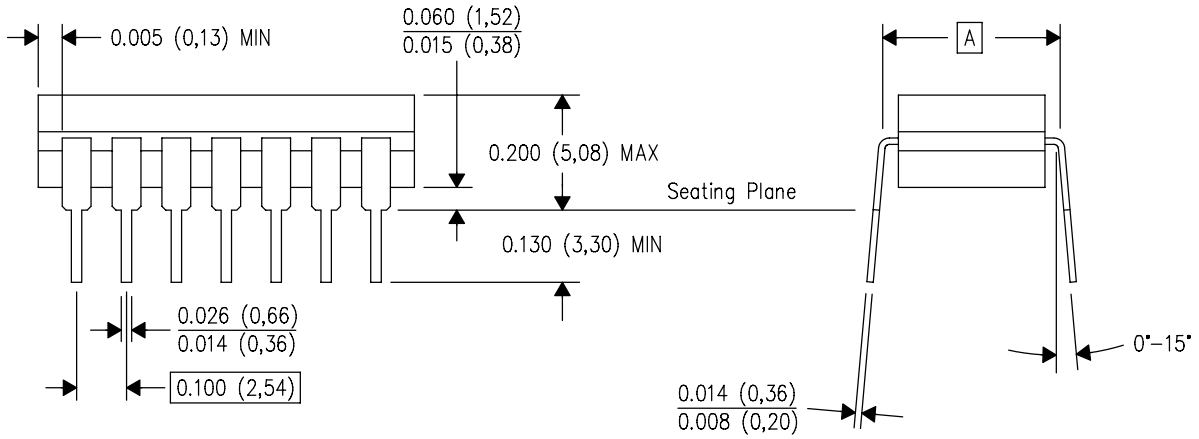
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



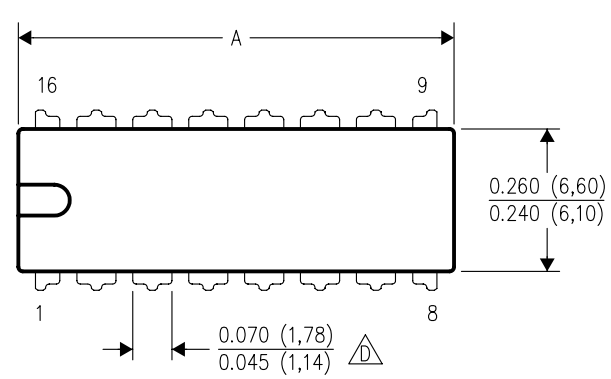
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

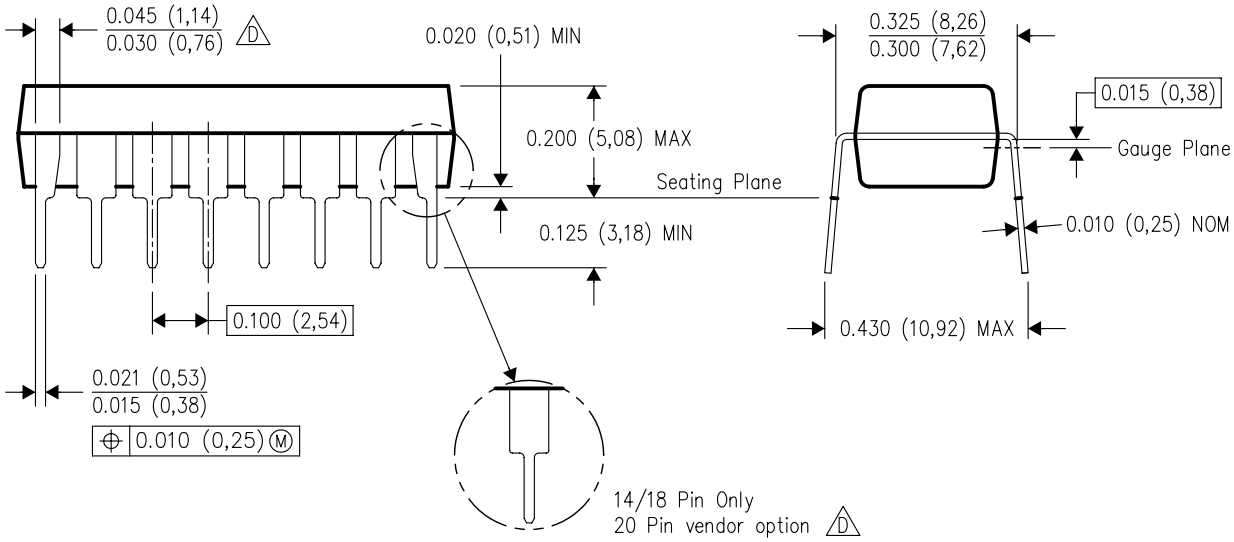
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

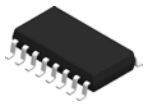


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

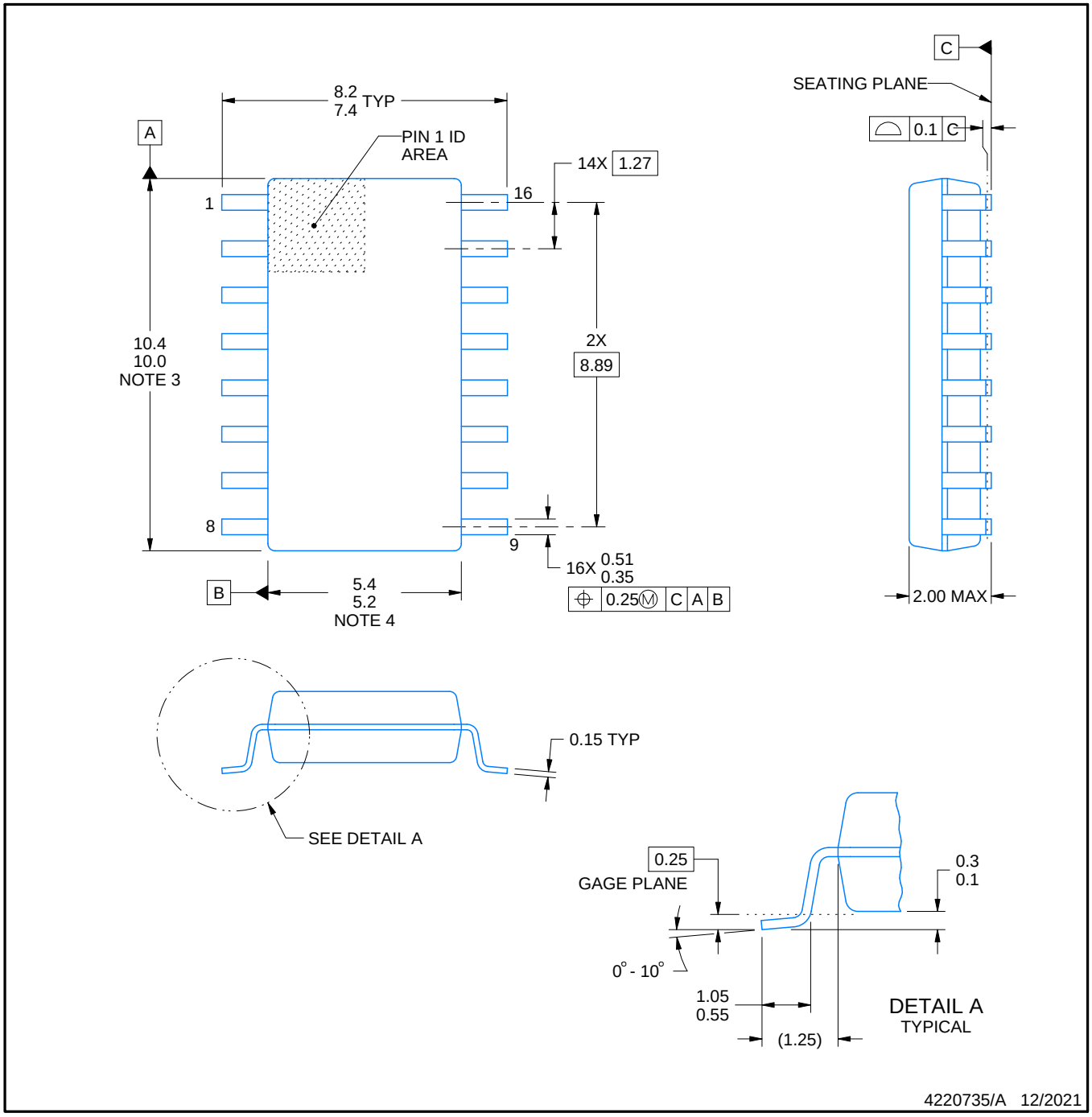


PACKAGE OUTLINE

NS0016A

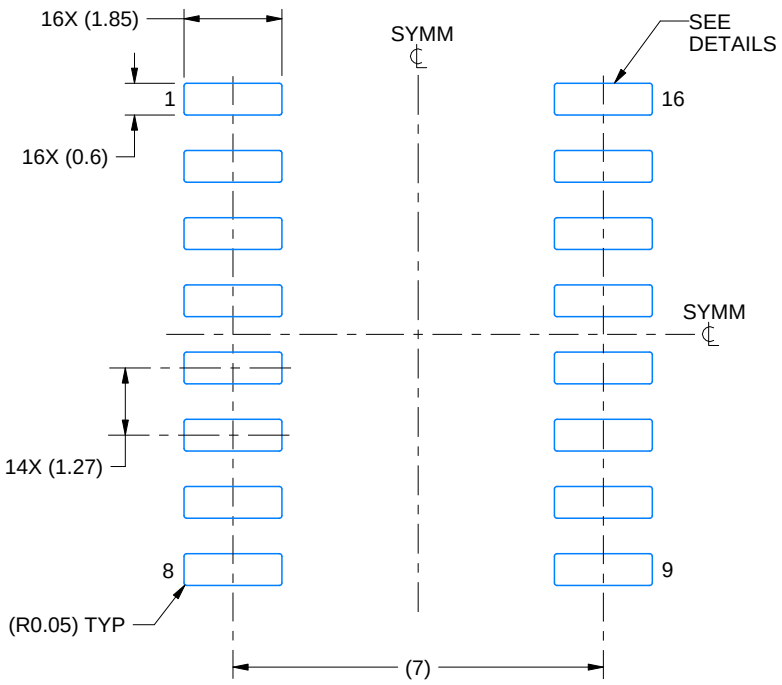
SOP - 2.00 mm max height

SOP

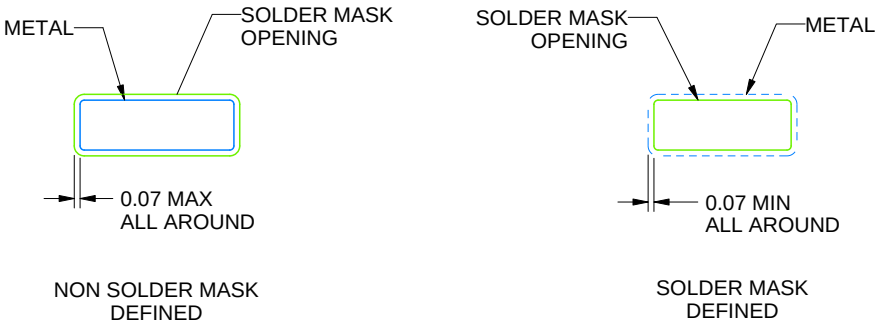


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



LAND PATTERN EXAMPLE
SCALE:7X



NON SOLDER MASK
DEFINED

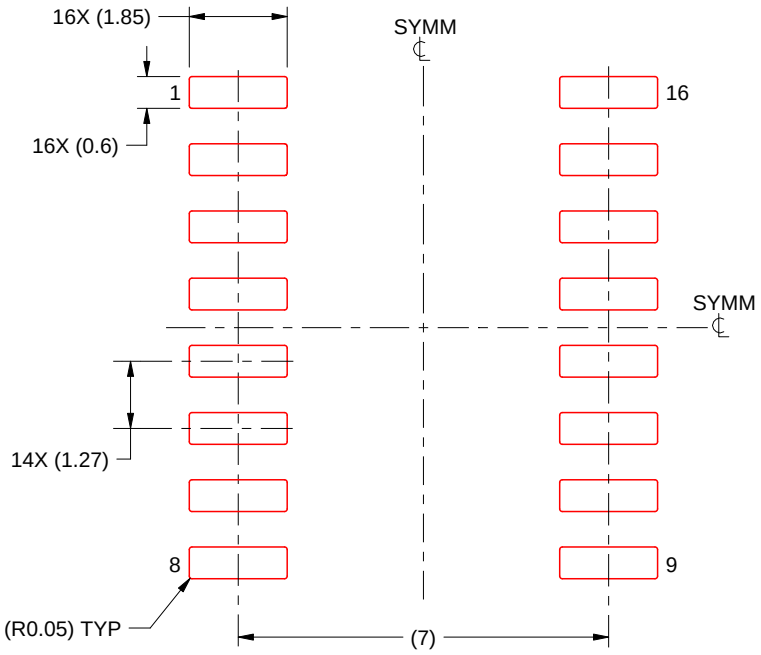
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A 12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



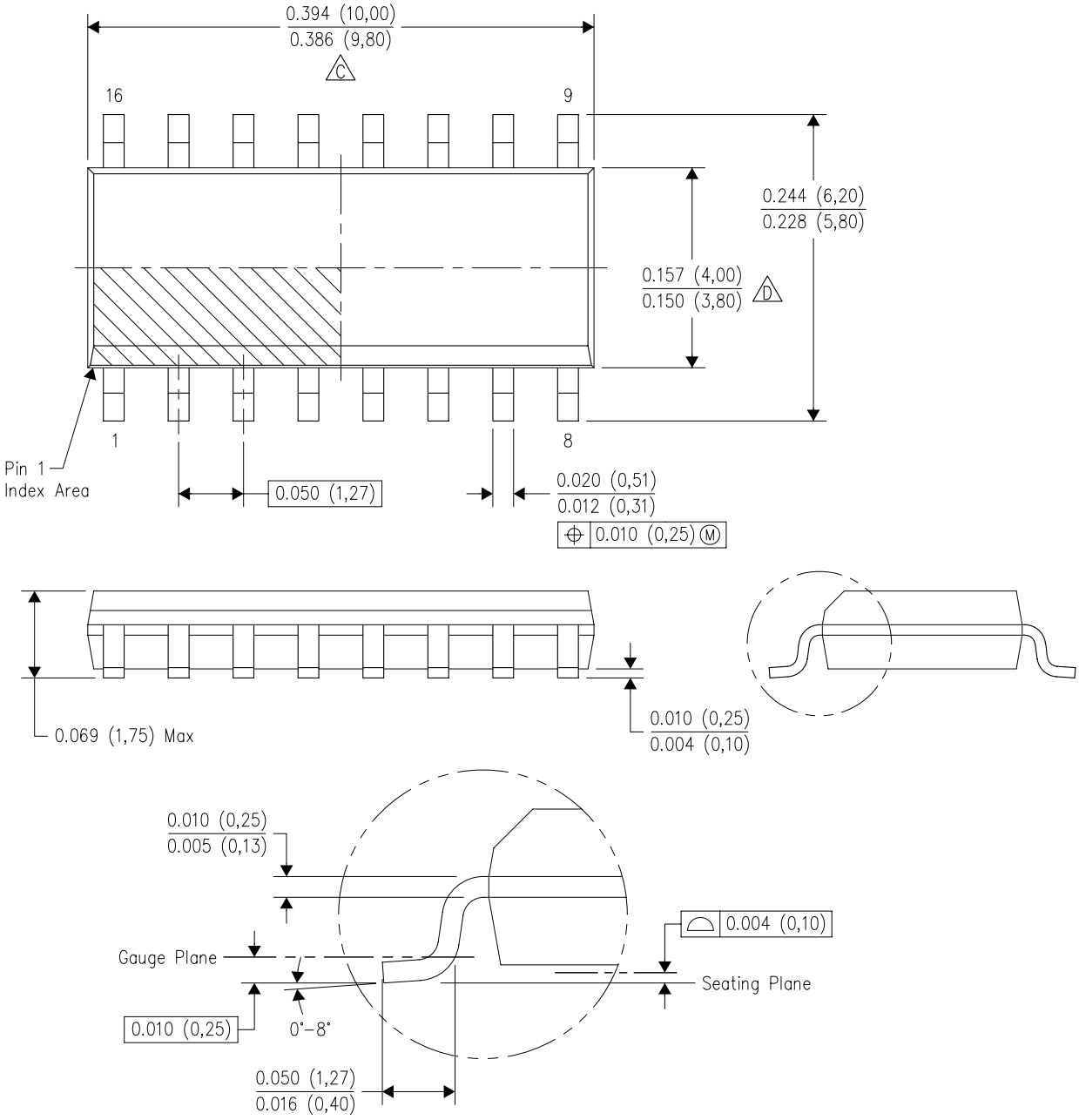
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



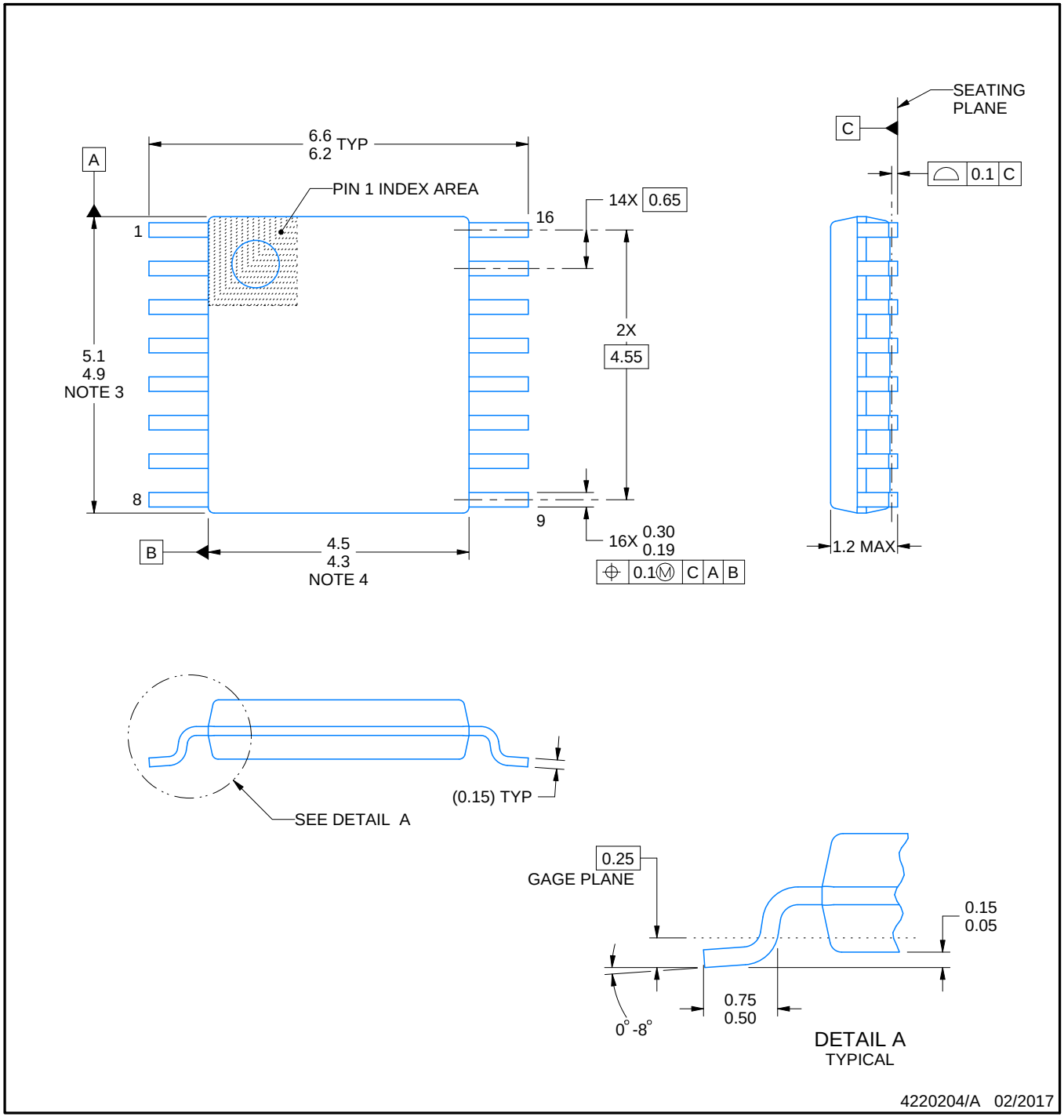
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

PACKAGE OUTLINE

PW0016A

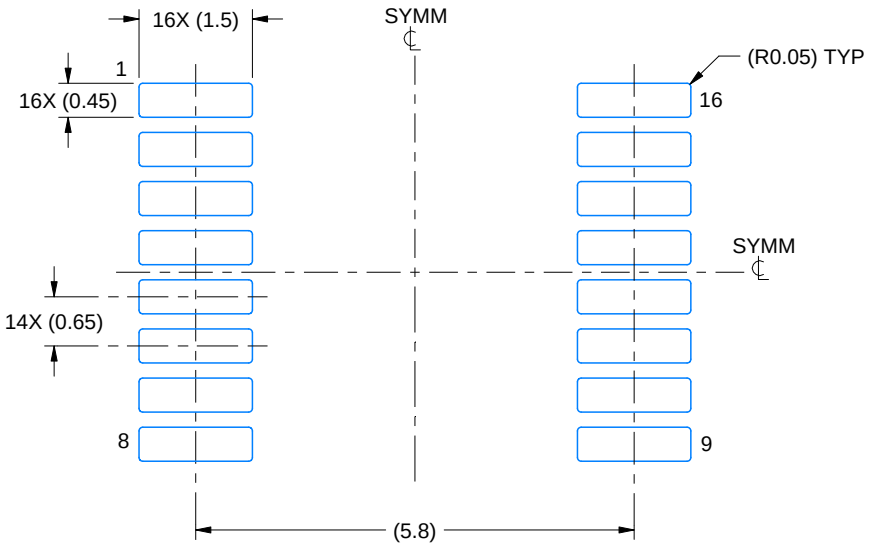
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

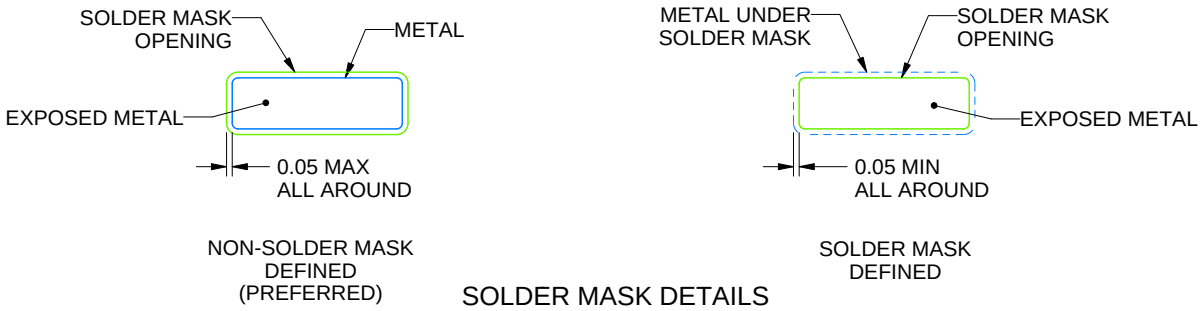


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

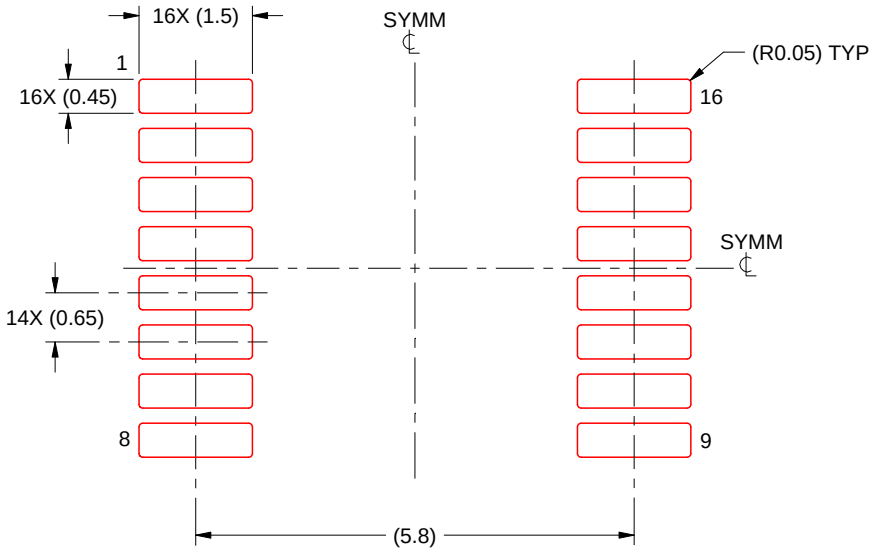


SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

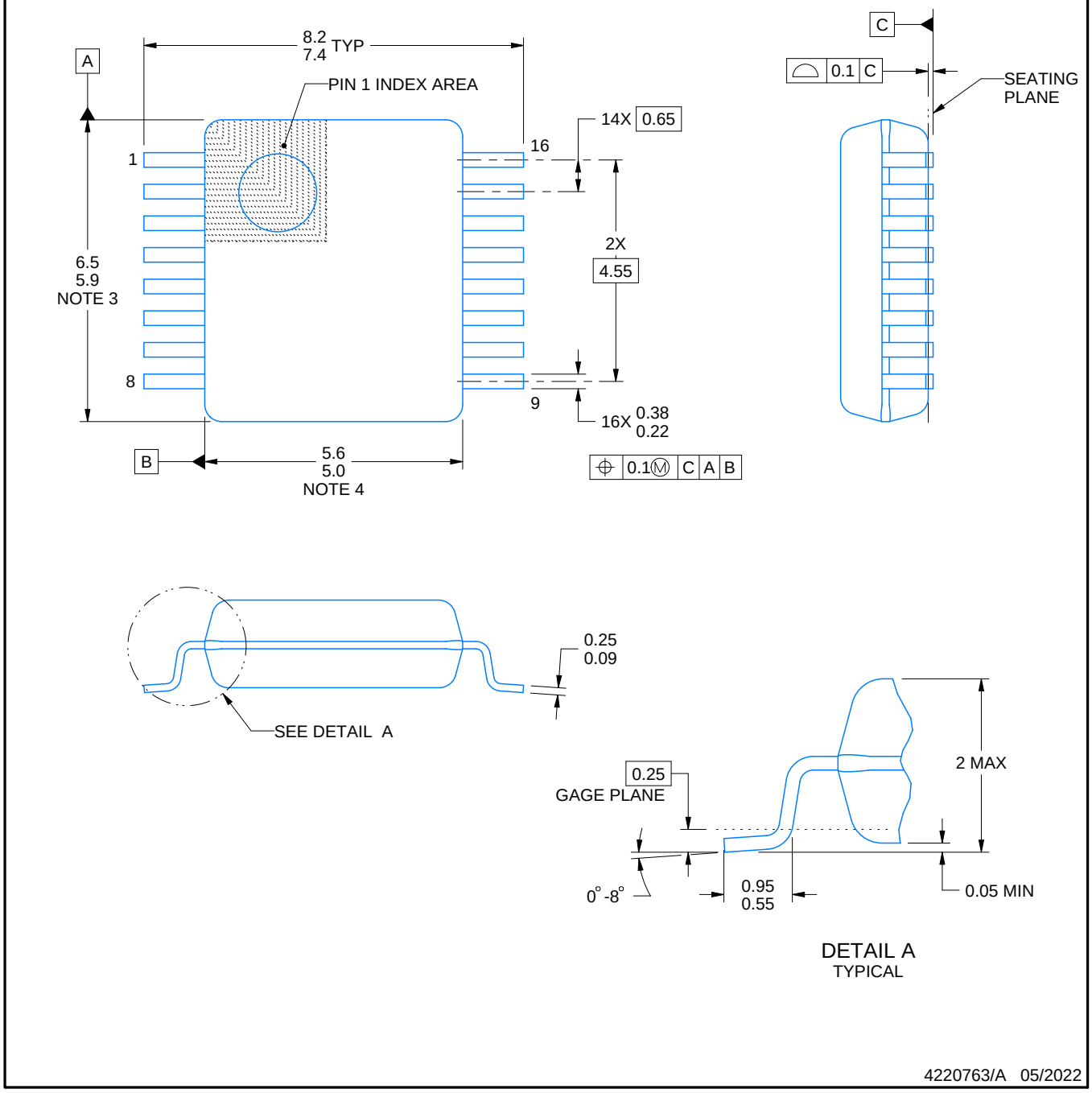
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DB0016A

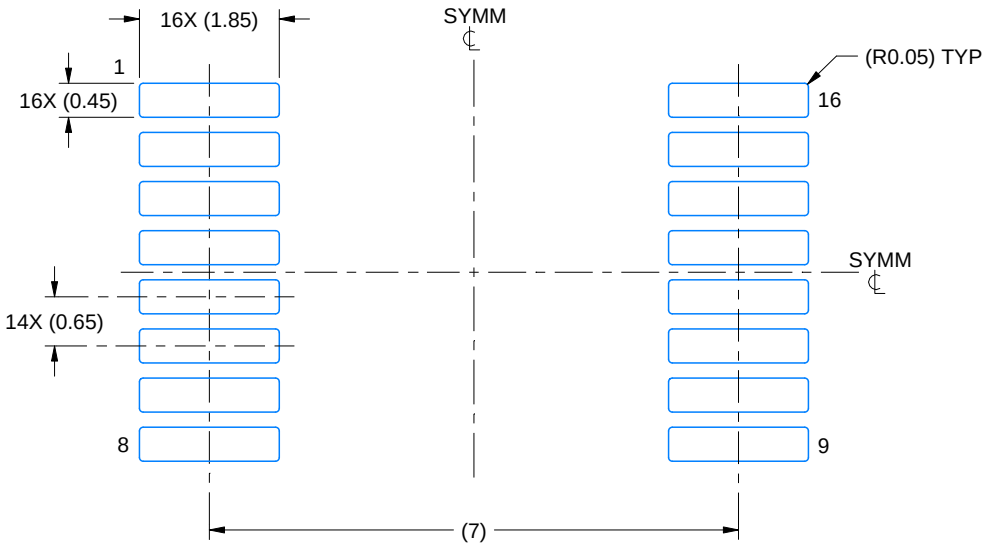
SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

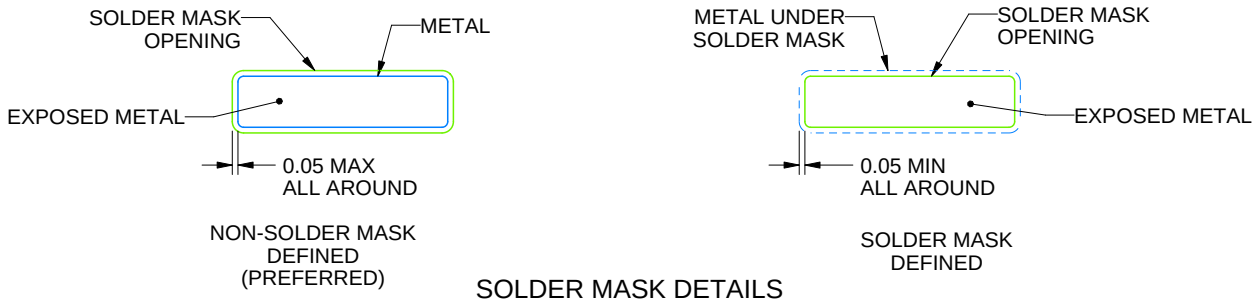


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

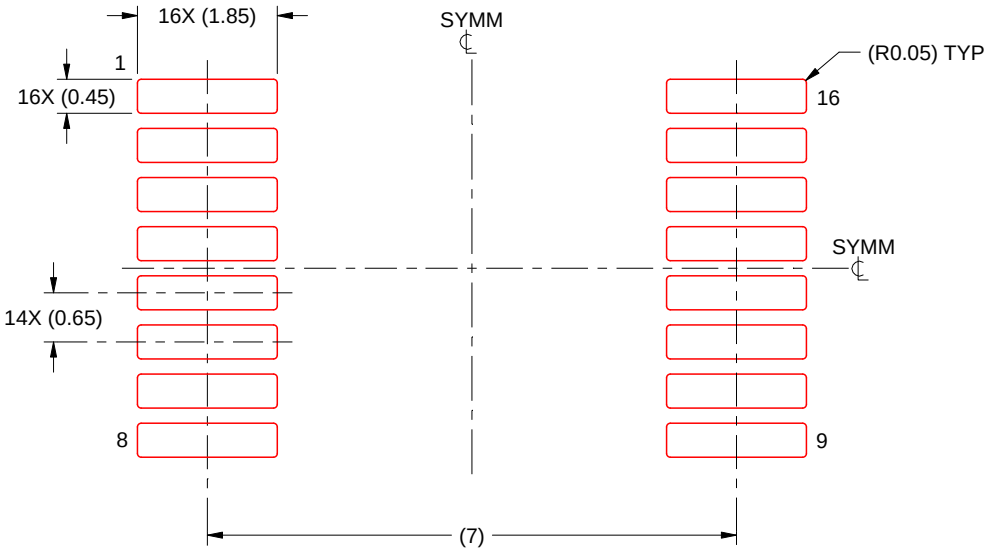


SOLDER MASK DETAILS

4220763/A 05/2022

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A 05/2022

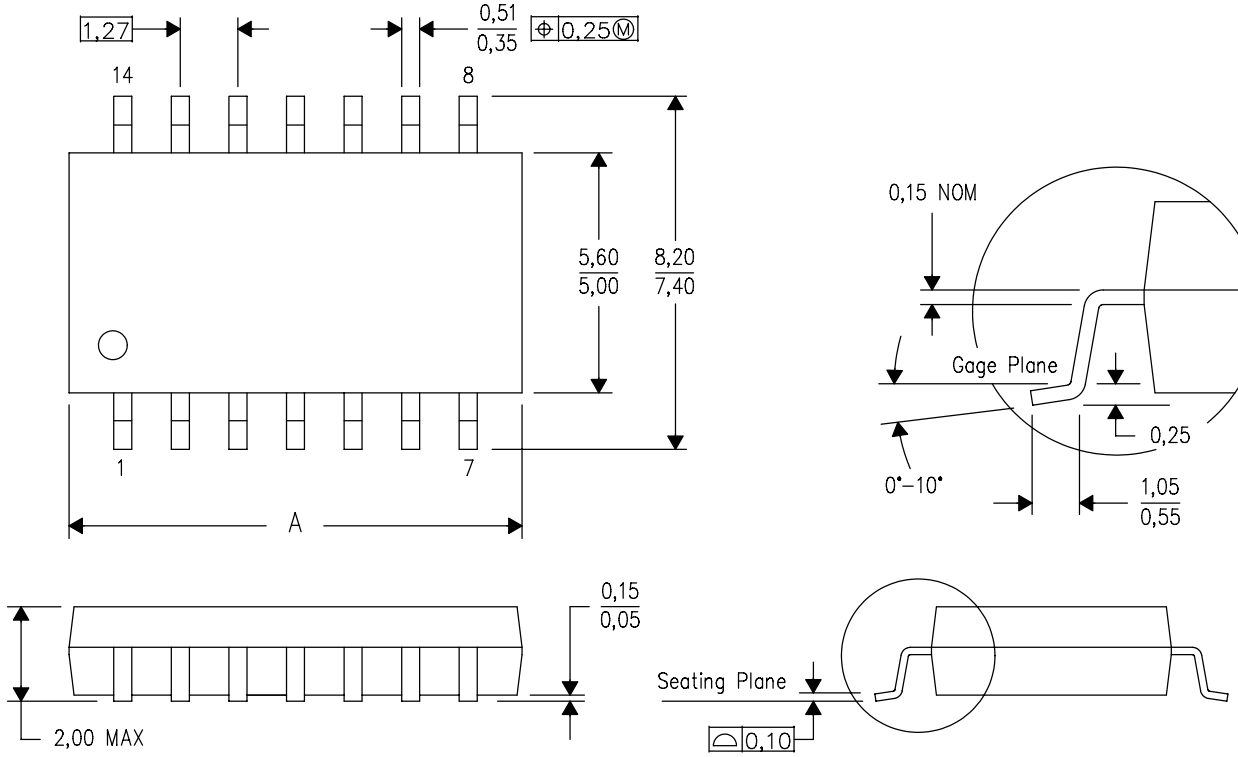
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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